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**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTOR: Mahesh Sanganeria et al. ) EXAMINER: Minh Loan Tran

SERIAL NO.: 10/647,773 ) ART UNIT: 2826

FILING DATE: August 25, 2003 ) DATE: October 4, 2004

FOR: METHOD OF IMPROVING

ADHESION BETWEEN TWO

**DIELECTRIC FILMS** 

## **RESPONSE TO RESTRICTION REQUIREMENT**

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Responsive to the Restriction Requirement Office Action mailed September 8, 2004, applicants provisionally elect Group I, claims 1-23, drawn to a process.

The Examiner has restricted the invention of the subject application to one of the following inventions:

Group I Claims 1-23 Drawn to a process for making electronic

components having improving adhesion

between an insulating layer and a capping

layer, classified in class 438, subclass 644;

and

Group II Claims 24-29 Drawn to a semiconductor structure,

classified in class 257, subclass 753.

Applicants respectfully traverse the restriction requirement on the grounds that 35 USC § 121 authorizes restriction only when the claimed invention is "independent